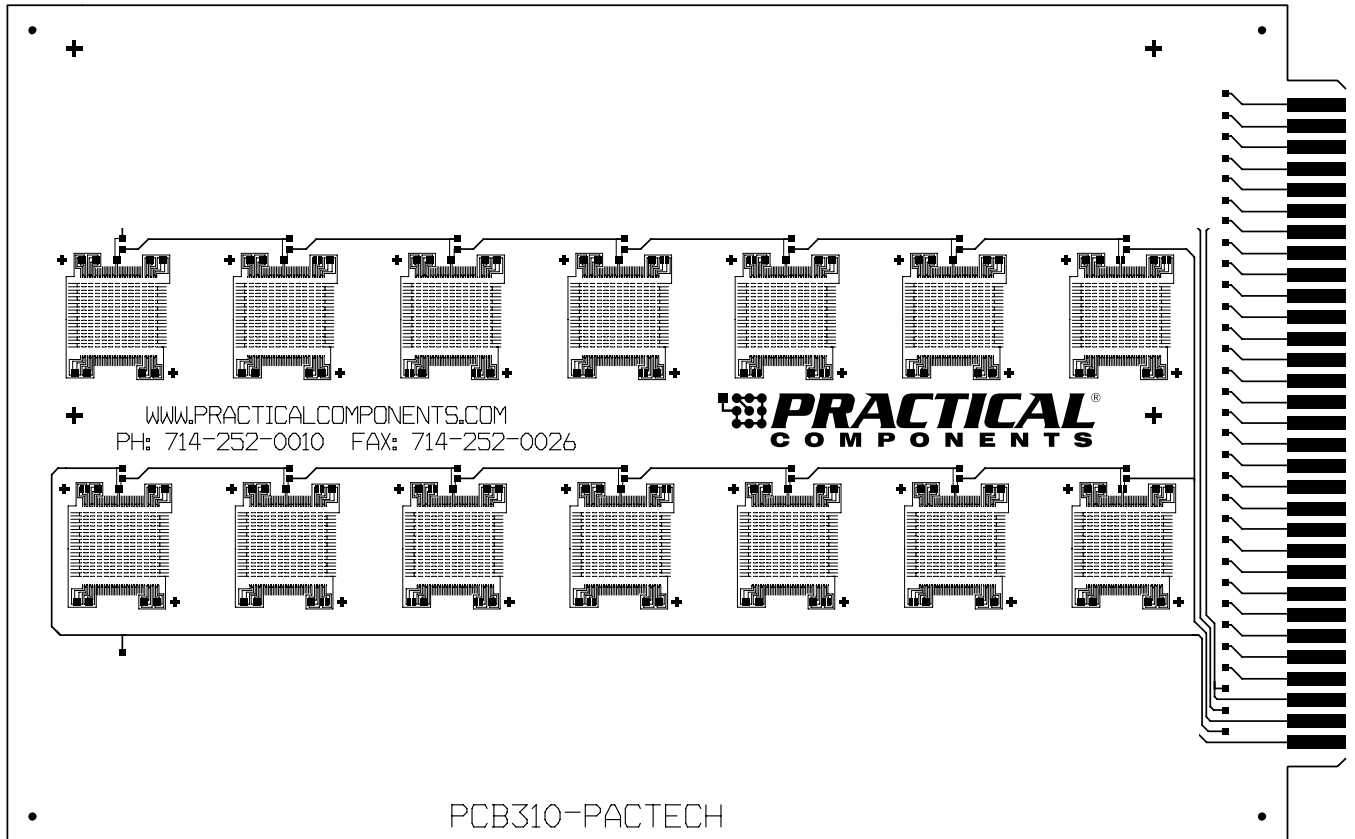


PACTECH Flip Chip Test and Evaluation Kit and Board

Introduction (taken from Website)

The PACTECH Flip Chip Test & Evaluation board is for placement and daisy chain continuity testing after assembly. Substrate has 14 mounting sites for 10 x 10mm Flip Chips. With an increasing number of I/O's on Integrated Circuits and accompanying requirements for high performance, flip chip type components are a compelling technology for potential users. PACTECH test die are combined with test boards to provide customers

with the ability to test a variety of specs and processes. The components and test board are daisy-chained for continuity. The PCB310 PacTech Board is single sided with 14 pads to accommodate 2 rows of 7 Pac2.3-572-200/400-10mm die each.



Notes

- Board size is 6.3" x 3.95", 2 layers, .062" thick.
- Board material is IS410-High Temp 180Tg.
- Standard board finish OSP Entek CU-A-HT.
- Gerber and X,Y Theta data included at no charge.
- See page 38 for available solder ball alloys.

Order Number: 12299 PCB310-PACTECH (board only)

Order Number: 12312 Pac2.3-FA572-200/400-10mm-DC-305 (Rows 2 and 3)

